





SOLUTIONS PRODUCTS DESIGN SUPPORT

BUY & SAMPLE

ABOUT CYPRESS

Home > Products > Memories for Embedded Systems > nvSRAM > nvSRAM Serial > CY14MB064Q2A-SXQ

CY14MB064Q2A-SXQ RoHS PB Free

Status: In Production Datasheet



English

(pdf, 1.03 MB) File Type: PDF

Updated: Feb 22, 2016

CY14MB064Q2A-SXQ	
Automotive Qualified	N
Density (Kb)	64
Frequency (MHz)	40
Interface	SPI
Max. Operating Temp. (°C)	105
Max. Operating VCCQ (V)	3.60
Max. Operating Voltage (V)	3.60
Min. Operating Temp. (°C)	-40
Min. Operating VCCQ (V)	2.70
Min. Operating Voltage (V)	2.70
Organization (X x Y)	8Kb x 8
Part Family	Serial nvSRAM
Speed (ns)	0
Tape & Reel	N
Temp. Classification	Industrial(Q)

PRICING & INVENTORY AVAILABILITY

Availability	Quantity	Ships In	Buy from Cypress	Buy from Distributors
In Stock	7	24-48 hours	Contact Sales	Buy

^{*} Prices are shown in United States dollars and are for budgetary use only for volume of 1ku

PACKAGING/ORDERING	
Package	SOIC
No. of Pins	8
Package Dimensions	193 L x 1.5 H x 150 W (Mils)
Package Weight	76.45 (mgs)
Package Cross Section Drawing	Download
Package Carrier	TUBE
Package Carrier Drawing / Orientation	Drawing , Package Orientation
Standard Pack Quantity	194
Minimum Order Quantity (MOQ)	194
Order Increment	194
Estimated Lead Time (days)	28
ownloaded from Arrow.com.	32.0040

DESIGN SUPPORT

Development Kits

Forums

Knowledge Base

Packaging

Product Brochures

Quality & Reliability

Samples

Technical Support

Technical Training

Third Party Network (CYPros)

TRAINING

Workshops

Training On-Demand

Webinars

ECCN	(B.2.A.)
ECCN Suball	3A991

QUALITY AND ROHS			
Moisture Sensitivity Level (MSL)	3		
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)		
RoHS Compliant	Y Print RoHS Certificate of Compliance		
PB Free	Υ		
Lead/Ball Finish	Ni/Pd/Au		
Marking	Cypress Marking Format		

Package Material Declaration

8L-SOIC Pb-Free Package Material Declaration Datasheet Last Update: Feb 13, 2017

IPC 1752 Material Declaration

IPC1752 MATERIAL DECLARATION SOIC08 (SZ08)- AMKOR PHIL - AU WIRE *Last Update: Nov 10, 2016*IPC1752 MATERIAL DECLARATION SOIC 08 (SZ08) - CML - AU WIRE *Last Update: Nov 10, 2016*IPC1752 MATERIAL DECLARATION SOIC 08 (SZ08) - OSE - AU WIRE *Last Update: Nov 10, 2016*

RoHS Analysis Certificates (CoA) for Direct Materials

Please click here

Device Qualification Reports

FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report.

QTP 102204: 1MEG (INDUS) SERIAL NON-VOLATILE SRAM PRODUCT FAMILY, S8 TECHNOLOGY, CMI (FAB 4).pdf Last Update: Sep 15, 2016

TECHNICAL DOCUMENTS

Product Change Notice (PCN) (1)

PCN135221 Feb 08, 2016

Qualification of Copper Wire Bonds for select Lead Frame Products at Amko Philippines andn Cypress Philippines and transfer of PDIP and PLCC parts from MMT to Amkor

Product Information Notice (PIN) (3)

PIN135200 Feb 05, 2016

Barcode Inclusion on Cypress Packing List

PIN145273 Feb 05, 2016

Improvement of Cypress Minnesota Back-End-of-Line Integration for 130nm SONOS Product Families

Droducts

PIN145277 Feb 05, 2016

Changes to Cypress Address Labels

Solutions

Solutions	Products	Design Support	buy & Sample	
Automotive	Wireless	Community	Request Samples	
Industrial	Microcontrollers (MCUs)	Videos	Buy Devices	
Consumer	Universal Serial Bus	Development Kits	Buy Development Kits	
	(USB)	Quality & Reliability	About Us	
	Memory	Product Roadmaps		
	Touch Sensing		Investors	
	Power Management		Careers	
	Clocks & Buffers			

Design Support

Ruy & Sample

CORPORATE HEADQUARTERS

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CUSTOMER SERVICE SUPPORT INTERNATIONAL SUPPORT

OTHER REQUESTS

Contact Us Report a Website

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(pacific time)

ABOUT US CAREERS INVESTORS

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